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# **RE46C190**

### CMOS Low Voltage Photoelectric Smoke Detector ASIC with Interconnect and Timer Mode

#### Features

- Two AA Battery Operation
- Internal Power On Reset
- Low Quiescent Current Consumption
- Available in 16L N SOIC
- · Local Alarm Memory
- Interconnect up to 40 Detectors
- 9 Minute Timer for Sensitivity Control
- Temporal or Continuous Horn Pattern
- Internal Low Battery and Chamber Test
- · All Internal Oscillator
- Internal Infrared Emitter Diode (IRED) driver
- · Adjustable IRED Drive current
- Adjustable Hush Sensitivity
- · 2% Low Battery Set Point

#### Description

The RE46C190 is a low power, low voltage CMOS photoelectric type smoke detector IC. With minimal external components, this circuit will provide all the required features for a photoelectric-type smoke detector.

The design incorporates a gain-selectable photo amplifier for use with an infrared emitter/detector pair.

An internal oscillator strobes power to the smoke detection circuitry every 10 seconds, to keep the standby current to a minimum. If smoke is sensed, the detection rate is increased to verify an Alarm condition. A high gain mode is available for push button chamber testing.

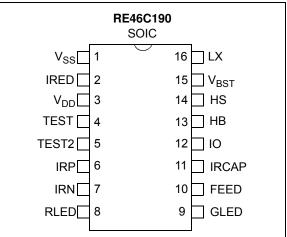
A check for a low battery condition is performed every 86 seconds, and chamber integrity is tested once every 43 seconds, when in Standby. The temporal horn pattern supports the NFPA 72 emergency evacuation signal.

An interconnect pin allows multiple detectors to be connected such that, when one unit alarms, all units will sound.

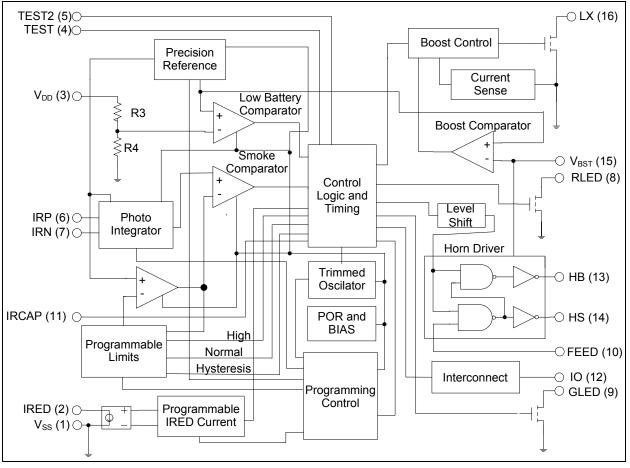
An internal 9 minute timer can be used for a Reduced Sensitivity mode.

Utilizing low power CMOS technology, the RE46C190 was designed for use in smoke detectors that comply with Underwriters Laboratory Specification UL217 and UL268.

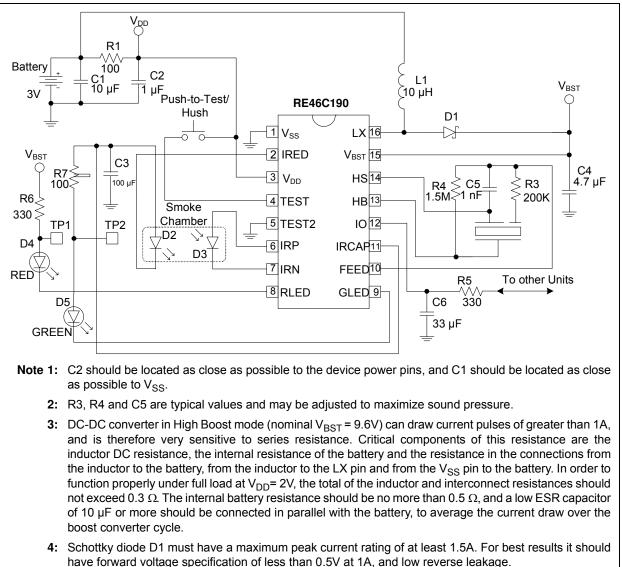
#### **PIN CONFIGURATION**



#### TYPICAL BLOCK DIAGRAM



#### **TYPICAL BATTERY APPLICATION**



5: Inductor L1 must have a maximum peak current rating of at least 1.5A.

NOTES:

#### 1.0 ELECTRICAL CHARACTERISTICS

#### **Absolute Maximum Ratings†**

Supply VoltageV_DD=5.5V; V_BST =13V
Input Voltage Range Except FEED, TEST V <sub>IN</sub> =3V to V <sub>DD</sub> +.3V
FEED Input Voltage Range V <sub>INFD</sub> =-10 to +22V
TEST Input Voltage Range V <sub>INTEST</sub> =3V to V <sub>BST</sub> +.3V
Input Current except FEEDI <sub>IN</sub> = 10 mA
Continuous Operating Current (HS, HB, V_{BST}) I_O= 40 mA
Continuous Operating Current (IRED)I <sub>OIR</sub> = 300 mA
Operating Temperature $T_A = -10$ to +60°C
Storage TemperatureT <sub>STG</sub> = -55 to +125°C
ESD Human Body Model V <sub>HBM</sub> = 750V
ESD Machine Model

**†** Notice: Stresses above those listed under "Maximum ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

#### DC ELECTRICAL CHARACTERISTICS

**DC Electrical Characteristics:** Unless otherwise indicated, all parameters apply at  $T_A = -10$  to +60°C,  $V_{DD} = 3V$ ,  $V_{BST} = 4.2V$ , Typical Application (unless otherwise noted)(Note 1, Note 2, Note 3)

Parameter	Symbol	Test Pin	Min	Тур	Max	Units	Conditions
Supply Voltage	V <sub>DD</sub>	3	2	_	5.0	V	Operating
Supply Current	I <sub>DD1</sub>	3	_	1	2	μA	Standby, Inputs Iow, No loads, Boost Off, No smoke check
Standby Boost Current	I <sub>BST1</sub>	15	_	100	_	nA	Standby, Inputs Iow, No loads, Boost Off, No smoke check
IRCAP Supply Current	I <sub>IRCAP</sub>	11	_	500	—	μA	During smoke check
Boost Voltage	V <sub>BST1</sub>	15	3.0	3.6	4.2	V	IRCAP charging for Smoke Check, GLED operation I <sub>OUT</sub> = 40 mA
	V <sub>BST2</sub>	15	8.5	9.6	10.7	V	No local alarm, RLED Operation, I <sub>OUT</sub> = 40 mA, IO as an input
Input Leakage	I <sub>INOP</sub>	6	-200	_	200	pА	IRP = V <sub>DD</sub> or V <sub>SS</sub>
		7	-200	—	200	pА	IRN = $V_{DD}$ or $V_{SS}$
	I <sub>IHF</sub>	10	-	20	50	μA	FEED = 22V; V <sub>BST</sub> = 9V
	I <sub>ILF</sub>	10	-50	-15	_	μA	FEED = -10V; V <sub>BST</sub> = 10.7V
Input Voltage Low	V <sub>IL1</sub>	10	_	_	2.7	V	FEED, V <sub>BST</sub> = 9V
	V <sub>IL2</sub>	12	_	—	800	mV	No local alarm, IO as an input

**Note 1:** Wherever a specific V<sub>BST</sub> value is listed under test conditions, the V<sub>BST</sub> is forced externally with the inductor disconnected and the DC-DC converter NOT running.

2: Typical values are for design information only.

**3:** Limits over the specified temperature range are not production tested and are based on characterization data. Unless otherwise stated, production test is at room temperature with guardbanded limits.

4: Not production tested.

#### DC ELECTRICAL CHARACTERISTICS (CONTINUED)

**DC Electrical Characteristics:** Unless otherwise indicated, all parameters apply at  $T_A = -10$  to  $+60^{\circ}$ C,  $V_{DD} = 3$ V,  $V_{BST} = 4.2$ V, Typical Application (unless otherwise noted)(Note 1, Note 2, Note 3)

$V_{BST}$ = 4.2V, Typical A	Application (u	inless oth	erwise note	d)( <b>Note 1, I</b>	Note 2, Note	<b>3</b> )	i
Parameter	Symbol	Test Pin	Min	Тур	Max	Units	Conditions
Input Voltage High	V <sub>IH1</sub>	10	6.2	—	_	V	FEED; V <sub>BST</sub> = 9V
	V <sub>IH2</sub>	12	2.0	—	—	V	No local alarm, IO as an input
IO Hysteresis	V <sub>HYST1</sub>	12	—	150	—	mV	
Input Pull Down	I <sub>PD1</sub>	4, 5	0.25	—	10	μA	$V_{IN} = V_{DD}$
Current	I <sub>PDIO1</sub>	12	20	—	80	μA	$V_{IN} = V_{DD}$
	I <sub>PDIO2</sub>	12	_	—	140	μA	V <sub>IN</sub> = 15V
Output Voltage Low	V <sub>OL1</sub>	13, 14	—	—	1	V	I <sub>OL</sub> = 16 mA, V <sub>BST</sub> = 9V
	V <sub>OL2</sub>	8	_	—	300	mV	I <sub>OL</sub> = 10 mA, V <sub>BST</sub> = 9V
	V <sub>OL3</sub>	9	_	_	300	mV	I <sub>OL</sub> = 10 mA, V <sub>BST</sub> = 3.6V
Output High Voltage	V <sub>OH1</sub>	13, 14	8.5	_	—	V	I <sub>OL</sub> = 16 mA, V <sub>BST</sub> = 9V
Output Current	I <sub>IOH1</sub>	12	-4	-5	—	mA	Alarm, V <sub>IO</sub> = 3V or V <sub>IO</sub> = 0V, V <sub>BST</sub> = 9V
	I <sub>IODMP</sub>	12	5	30	—	mA	At Conclusion of Local Alarm or Test, V <sub>IO</sub> =1V
	I <sub>IRED50</sub>	2	45	50	55	mA	IRED on, $V_{IRED} = 1V$ , $V_{BST} = 5V$ , IRCAP = 5V, (50 mA option selected; $T_A = 27^{\circ}C$ )
	I <sub>IRED100</sub>	2	90	100	110	mA	IRED on, $V_{IRED} = 1V$ , $V_{BST} = 5V$ , IRCAP = 5V, (100 mA option selected; $T_A = 27^{\circ}C$ )
	I <sub>IRED150</sub>	2	135	150	165	mA	IRED on, $V_{IRED} = 1V$ , $V_{BST} = 5V$ , IRCAP = 5V, (150 mA option selected; $T_A = 27^{\circ}C$ )
	I <sub>IRED2050</sub>	2	180	200	220	mA	IRED on, $V_{IRED} = 1V$ , $V_{BST} = 5V$ , IRCAP = 5V, (200 mA option selected; $T_A = 27^{\circ}C$ )
IRED Current Temperature Coefficient	TC <sub>IRED</sub>			0.5		%/°C	V <sub>BST</sub> = 5V, IRCAP = 5V; Note 4

**Note 1:** Wherever a specific V<sub>BST</sub> value is listed under test conditions, the V<sub>BST</sub> is forced externally with the inductor disconnected and the DC-DC converter NOT running.

2: Typical values are for design information only.

**3:** Limits over the specified temperature range are not production tested and are based on characterization data. Unless otherwise stated, production test is at room temperature with guardbanded limits.

4: Not production tested.

#### DC ELECTRICAL CHARACTERISTICS (CONTINUED)

**DC Electrical Characteristics:** Unless otherwise indicated, all parameters apply at  $T_A = -10$  to  $+60^{\circ}$ C,  $V_{DD} = 3$ V,  $V_{BST} = 4.2$ V, Typical Application (unless otherwise noted)(Note 1, Note 2, Note 3)

V <sub>BST</sub> = 4.2V, Typical Application (unless otherwise noted)(Note 1, Note 2, Note 3)									
Parameter	Symbol	Test Pin	Min	Тур	Max	Units	Conditions		
Low Battery Alarm Voltage	V <sub>LB1</sub>	3	2.05	2.1	2.15	V	Falling Edge; 2.1V nominal selected		
	V <sub>LB2</sub>	3	2.15	2.2	2.25	V	Falling Edge; 2.2V nominal selected		
	V <sub>LB3</sub>	3	2.25	2.3	2.35	V	Falling Edge; 2.3V nominal selected		
	V <sub>LB4</sub>	3	2.35	2.4	2.45	V	Falling Edge; 2.4V nominal selected		
	V <sub>LB5</sub>	3	2.45	2.5	2.55	V	Falling Edge; 2.5V nominal selected		
	V <sub>LB6</sub>	3	2.55	2.6	2.65	V	Falling Edge; 2.6V nominal selected		
	V <sub>LB7</sub>	3	2.65	2.7	2.75	V	Falling Edge; 2.7V nominal selected		
	V <sub>LB8</sub>	3	2.75	2.8	2.85	V	Falling Edge; 2.8V nominal selected		
Low Battery Hysteresis	V <sub>LBHYST</sub>	3	—	100		mV			
IRCAP Turn On Voltage	V <sub>TIR1</sub>	11	3.6	4.0	4.4	V	Falling edge; V <sub>BST</sub> = 5V; I <sub>OUT</sub> = 20 mA		
IRCAP Turn Off Voltage	V <sub>TIR2</sub>	11	4.0	4.4	4.8	V	Rising edge; V <sub>BST</sub> = 5V; I <sub>OUT</sub> = 20 mA		

**Note 1:** Wherever a specific V<sub>BST</sub> value is listed under test conditions, the V<sub>BST</sub> is forced externally with the inductor disconnected and the DC-DC converter NOT running.

2: Typical values are for design information only.

**3:** Limits over the specified temperature range are not production tested and are based on characterization data. Unless otherwise stated, production test is at room temperature with guardbanded limits.

4: Not production tested.

#### AC ELECTRICAL CHARACTERISTICS

**AC Electrical Characteristics:** Unless otherwise indicated, all parameters apply at  $T_A = -10^{\circ}$  to  $+60^{\circ}$ C,  $V_{DD} = 3$ V,  $V_{BST} = 4.2$ V, Typical Application (unless otherwise noted) (**Note 1** to **Note 4**).

Parameter	Symbol	Test Pin	Min	Тур	Max	Units	Condition
Time Base		11			1	1	
Internal Clock Period	T <sub>PCLK</sub>		9.80	10.4	11.0	ms	PROGSET, IO = high
RLED Indicator							·
On Time	T <sub>ON1</sub>	8	9.80	10.4	11.0	ms	Operating
Standby Period	T <sub>PLED1</sub>	8	320	344	368	S	Standby, no alarm
Local Alarm Period	T <sub>PLED2A</sub>	8	470	500	530	ms	Local alarm condition with temporal horn pattern
	T <sub>PLED2B</sub>	8	625	667	710	ms	Local alarm condition with continuous horn pattern
Hush Timer Period	T <sub>PLED4</sub>	8	10	10.7	11.4	S	Timer mode, no local alarm
External Alarm Period	T <sub>PLED0</sub>	8	LE	ED IS NOT (	ON	S	Remote alarm only
GLED Indicator							·
Latched Alarm Period	T <sub>PLED3</sub>	9	40	43	46	S	Latched Alarm Condition, LED enabled
Latched Alarm Pulse Train (3x) Off Time	T <sub>OFLED</sub>	9	1.25	1.33	1.41	S	Latched Alarm Condition, LED enabled
Latched Alarm LED Enabled Duration	T <sub>LALED</sub>	9	22.4	23.9	25.3	Hours	Latched Alarm Condition, LED enabled
Smoke Check							·
Smoke Test Period	T <sub>PER0A</sub>	2	10	10.7	11.4	S	Standby, no alarm
with Temporal Horn Pattern	T <sub>PER1A</sub>	2	1.88	2.0	2.12	S	Standby, after one valid smoke sample
	T <sub>PER2A</sub>	2	0.94	1.0	1.06	S	Standby, after two consecutive valid smoke samples
	T <sub>PER3A</sub>	2	0.94	1.0	1.06	S	Local Alarm (three consecutive valid smoke samples)
	T <sub>PER4A</sub>	2	235	250	265	ms	Push button test, >1 chamber detections
			313	333	353	ms	Push button test, no chamber detections
	T <sub>PER5A</sub>	2	7.5	8.0	8.5	S	In remote alarm

**Note 1:** See timing diagram for Horn Pattern (Figure 5-2).

2: T<sub>PCLK</sub> and T<sub>IRON</sub> are 100% production tested. All other AC parameters are verified by functional testing.

3: Typical values are for design information only.

4: Limits over the specified temperature range are not production tested, and are based on characterization data.

#### AC ELECTRICAL CHARACTERISTICS (CONTINUED)

**AC Electrical Characteristics:** Unless otherwise indicated, all parameters apply at  $T_A = -10^{\circ}$  to  $+60^{\circ}$ C,  $V_{DD} = 3$ V,  $V_{BST} = 4.2$ V, Typical Application (unless otherwise noted) (Note 1 to Note 4).

$V_{BST}$ = 4.2V, Typical A	pplication (	(unless othe	erwise note	d) (Note 1	to Note 4).	•	-
Parameter	Symbol	Test Pin	Min	Тур	Max	Units	Condition
Smoke Test Period	T <sub>PER0B</sub>	2	10	10.7	11.4	s	Standby, no alarm
with Continuous Horn Pattern	T <sub>PER1B</sub>	2	2.5	2.7	2.9	S	Standby, after one valid smoke sample
	T <sub>PER2B</sub>	2	1.25	1.33	1.41	S	Standby, after two consecutive valid smoke samples
	T <sub>PER3B</sub>	2	1.25	1.33	1.41	S	Local Alarm (three consecutive valid smoke samples)
	T <sub>PER4B</sub>	2	313	333	353	ms	Push button test
	T <sub>PER5B</sub>	2	10	10.7	11.4	S	In remote alarm
Chamber Test Period	T <sub>PCT1</sub>	2	40	43	46	S	Standby, no alarm
Long Term Drift Sample Period	T <sub>LTD</sub>	2	400	430	460	S	Standby, no alarm LTD enabled
Low Battery							
Low Battery Sample	T <sub>PLB1</sub>	3	320	344	368	S	RLED on
Period	T <sub>PLB2</sub>	3	80	86	92	s	RLED on
Horn Operation							
Low Battery Horn Period	T <sub>HPER1</sub>	13	40	43	46	S	Low battery, no alarm
Chamber Fail Horn Period	T <sub>HPER2</sub>	13	40	43	46	S	Chamber failure
Low Battery Horn On Time	T <sub>HON1</sub>	13	9.8	10.4	11.0	ms	Low battery, no alarm
Chamber Fail Horn On Time	T <sub>HON2</sub>	13	9.8	10.4	11.0	ms	Chamber failure
Chamber Fail Off Time	T <sub>HOF1</sub>	13	305	325	345	ms	Failed chamber, no alarm, 3x chirp option
Alarm On Time with Temporal Horn Pattern	T <sub>HON2A</sub>	13	470	500	530	ms	Local or remote alarm (Note 1)
Alarm Off Time with Temporal Horn	T <sub>HOF2A</sub>	13	470	500	530	ms	Local or remote alarm (Note 1)
Pattern	T <sub>HOF3A</sub>	13	1.4	1.5	1.6	S	Local or remote alarm (Note 1)
Alarm On Time with Continuous Horn Pattern	T <sub>HON2B</sub>	13	235	250	265	ms	Local or remote alarm (Note 1)
Alarm Off Time with Continuous Horn Pattern	T <sub>HOF2B</sub>	13	78	83	88	ms	Local or remote alarm (Note 1)

**Note 1:** See timing diagram for Horn Pattern (Figure 5-2).

2: T<sub>PCLK</sub> and T<sub>IRON</sub> are 100% production tested. All other AC parameters are verified by functional testing.

3: Typical values are for design information only.

4: Limits over the specified temperature range are not production tested, and are based on characterization data.

#### AC ELECTRICAL CHARACTERISTICS (CONTINUED)

**AC Electrical Characteristics:** Unless otherwise indicated, all parameters apply at  $T_A = -10^{\circ}$  to +60°C,  $V_{DD} = 3V$ ,  $V_{BST} = 4.2V$ , Typical Application (unless otherwise noted) (Note 1 to Note 4).

V <sub>BST</sub> = 4.2V, Typical A	pplication (	uniess oth	erwise note	a) (Note 1	to <b>Note 4</b> ).	1	1	
Parameter	Symbol	Test Pin	Min	Тур	Max	Units	Condition	
Push-to-Test Alarm Memory On Time	T <sub>HON4</sub>	13	9.8	10.4	11.0	ms	Alarm memory active, push-to-test	
Push-to-Test Alarm Memory Horn Period	T <sub>HPER4</sub>	13	235	250	265	ms	Alarm memory active, push-to-test	
Interconnect Signal	Operation	(IO)						
IO Active Delay	T <sub>IODLY1</sub>	12	—	0	—	s	From start of local alarm to IO active	
Remote Alarm Delay with Temporal Horn Pattern	T <sub>IODLY2A</sub>	12	0.780	1.00	1.25	S	No local alarm, from IO active to alarm	
Remote Alarm Delay with Continuous Horn Pattern	T <sub>IODLY2B</sub>	12	380	572	785	ms	No local alarm, from IO active to alarm	
IO Charge Dump Duration	T <sub>IODMP</sub>	12	1.23	1.31	1.39	S	At conclusion of local alarm or test	
IO Filter	T <sub>IOFILT</sub>	12	_	—	313	ms	Standby, no alarm	
Hush Timer Operatio	n							
Hush Timer Period	T <sub>TPER</sub>		8.0	8.6	9.1	Min	No alarm	
EOL							•	
End-of-Life Age Sample	T <sub>EOL</sub>		314	334	354	Hours	EOL Enabled; Standby	
Detection								
IRED On Time	T <sub>IRON</sub>	2		100	_	μs	Prog Bits 3,4 = 1,1	
		2	_	200	_	μs	Prog Bits 3,4 = 0,1	
		2	_	300	—	μs	Prog Bits 3,4 = 1,0	
		2	_	400	_	μs	Prog Bits 3,4 = 0,0	

Note 1: See timing diagram for Horn Pattern (Figure 5-2).

2: T<sub>PCLK</sub> and T<sub>IRON</sub> are 100% production tested. All other AC parameters are verified by functional testing.

3: Typical values are for design information only.

4: Limits over the specified temperature range are not production tested, and are based on characterization data.

#### **TEMPERATURE CHARACTERISTICS**

<b>Electrical Specifications:</b> All limits specified for $V_{DD}$ = 3V, $V_{BST}$ = 4.2V and $V_{SS}$ = 0V, Except where noted in the Electrical Characteristics.										
Parameters Sym Min Typ Max Units Conditions										
Temperature Ranges										
Operating Temperature Range	Τ <sub>Α</sub>	-10	_	+60	°C					
Storage Temperature Range	T <sub>STG</sub>	-55	_	+125	°C					
Thermal Package Resistances										
Thermal Resistance, 16L-SOIC (150 mil.) θ <sub>JA</sub> — 86.1 — °C/W										

#### 2.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in Table 2-1.

RE46C190 SOIC	Symbol	Function
1	V <sub>SS</sub>	Connect to the negative supply voltage.
2	IRED	Provides a regulated and programmable pulsed current for the infrared emitter diode.
3	V <sub>DD</sub>	Connect to the positive supply or battery voltage.
4	TEST	This input is used to invoke Test modes and the Timer mode. This input has an internal pull-down.
5	TEST2	Test input for test and programming modes. This input has an internal pull-down.
6	IRP	Connect to the anode of the photo diode.
7	IRN	Connect to the cathode of the photo diode.
8	RLED	Open drain NMOS output, used to drive a visible LED. This pin provides load current for the low battery test, and is a visual indicator for Alarm and Hush modes.
9	GLED	Open drain NMOS output used to drive a visible LED to provide visual indication of an Alarm Memory condition.
10	FEED	Usually connected to the feedback electrode through a current limiting resistor. If not used, this pin must be connected to $V_{DD}$ or $V_{SS}.$
11	IRCAP	Used to charge and monitor the IRED capacitor.
12	IO	This bidirectional pin provides the capability to interconnect many detectors in a single system. This pin has an internal pull-down device and a charge dump device.
13	HB	This pin is connected to the metal electrode of a piezoelectric transducer.
14	HS	This pin is a complementary output to HB, connected to the ceramic electrode of the piezoelectric transducer.
15	V <sub>BST</sub>	Boosted voltage produced by DC-DC converter.
16	LX	Open drain NMOS output, used to drive the boost converter inductor. The inductor should be connected from this pin to the positive supply through a low resistance path.

#### TABLE 2-1: PIN FUNCTION TABLE

NOTES:

#### 3.0 DEVICE DESCRIPTION

#### 3.1 Standby Internal Timing

The internal oscillator is trimmed to  $\pm 6\%$  tolerance. Once every 10 seconds, the boost converter is powered up, the IRcap is charged from V<sub>BST</sub> and then the detection circuitry is active for 10 ms. Prior to completion of the 10 mS period, the IRED pulse is active for a user-programmable duration of 100-400 µs. During this IRED pulse, the photo diode current is integrated and then digitized. The result is compared to a limit value stored in EEPROM during calibration to determine the photo chamber status. If a smoke condition is present, the period to the next detection decreases, and additional checks are made.

#### 3.2 Smoke Detection Circuitry

The digitized photo amplifier integrator output is compared to the stored limit value at the conclusion of the IRED pulse period. The IRED drive is all internal, and both the period and current are user programmable. Three consecutive smoke detections will cause the device to go into Alarm and activate the horn and interconnect circuits. In Alarm, the horn is driven at the high boost voltage level, which is regulated based on an internal voltage reference, and therefore results in consistent audibility over battery life. RLED will turn on for 10 ms at a 2 Hz rate. In Local Alarm, the integration limit is internally decreased to provide alarm hysteresis. The integrator has three separate gain settings:

- · Normal and Hysteresis
- Reduced Sensitivity (HUSH)
- · High Gain for Chamber Test and Push-to-Test

There are four separate sets of integration limits (all user programmable):

- Normal Detection
- Hysteresis
- HUSH
- · Chamber Test and Push-to-Test modes

In addition, there are user selectable integrator gain settings to optimize detection levels (see Table 4-1).

#### 3.3 Supervisory Tests

Once every 86 seconds, the status of the battery voltage is checked by enabling the boost converter for 10 ms and comparing a fraction of the  $V_{DD}$  voltage to an internal reference. In each period of 344 seconds, the battery voltage is checked four times. Three checks are unloaded and one check is performed with the RLED enabled, which provides a battery load. The High Boost mode is active only for the loaded low battery test. In addition, once every 43 seconds the chamber is activated and a High Gain mode and chamber test limits are internally selected. A check of the chamber is made by amplifying background reflections. The Low Boost mode is used for the chamber test.

If either the low battery test or the chamber test fails, the horn will pulse on for 10 ms every 43 seconds, and will continue to pulse until the failing condition passes. If two consecutive chamber tests fail, the horn will pulse on three times for 10 ms, separated by 330 ms every 43 seconds. Each of the two supervisory test audible indicators is separated by approximately 20 seconds.

As an option, a Low Battery Silence mode can be invoked. If a low battery condition exists, and the TEST input is driven high, the RLED will turn on. If the TEST input is held for more than 0.5 second, the unit will enter the Push-to-test operation described in Section 3.4 "Push-to-Test Operation (PTT)". After the TEST input is driven low, the unit enters in Low Battery Hush mode, and the 10 ms horn pulse is silenced for 8 hours. The activation of the test button will also initiate the 9 minute Reduced Sensitivity mode described in Section 3.6 "Reduced Sensitivity Mode". At the end of the 8 hours, the audible indication will resume if the low battery condition still exists.

#### 3.4 Push-to-Test Operation (PTT)

If the TEST input pin is activated ( $V_{IH}$ ), the smoke detection rate increases to once every 250 ms after one internal clock cycle. In Push-to-Test, the photo amplifier High Gain mode is selected, and background reflections are used to simulate a smoke condition. After the required three consecutive detections, the device will go into a Local Alarm condition. When the TEST input is driven low ( $V_{IL}$ ), the photo amplifier Normal Gain is selected, after one clock cycle. The detection rate continues at once every 250 ms until three consecutive No Smoke conditions are detected. At this point, the device returns to standby timing. In addition, after the TEST input goes low, the device enters the HUSH mode (see Section 3.6 "Reduced Sensitivity Mode").

#### 3.5 Interconnect Operation

The bidirectional IO pin allows the interconnection of multiple detectors. In a Local Alarm condition, this pin is driven high (High Boost) immediately through a constant current source. Shorting this output to ground will not cause excessive current. The IO is ignored as input during a Local Alarm.

The IO pin also has an NMOS discharge device that is active for 1.3 seconds after the conclusion of any type of Local Alarm. This device helps to quickly discharge any capacitance associated with the interconnect line.

If a remote, active high signal is detected, the device goes into Remote Alarm and the horn will be active. RLED will be off, indicating a Remote Alarm condition. Internal protection circuitry allows the signaling unit to have a higher supply voltage than the signaled unit, without excessive current draw.

The interconnect input has a 336 ms nominal digital filter. This allows the interconnection to other types of alarms (carbon monoxide, for example) that may have a pulsed interconnect signal.

#### 3.6 Reduced Sensitivity Mode

A Reduced Sensitivity or Hush mode is initiated by activating the TEST input ( $V_{IH}$ ). If the TEST input is activated during a Local Alarm, the unit is immediately reset out of the alarm condition, and the horn is silenced. When the TEST input is deactivated ( $V_{IL}$ ), the device enters into a 9-minute nominal Hush mode. During this period, the HUSH integration limit is selected. The hush gain is user programmable. In Reduced Sensitivity mode, the RLED flashes for 10 ms every 10 seconds to indicate that the mode is active. As an option, the Hush mode will be cancelled if any of the following conditions exist:

- Reduced sensitivity threshold is exceeded (high smoke level)
- · An interconnect alarm occurs
- TEST input is activated again

#### 3.7 Local Alarm Memory

An Alarm Memory feature allows easy identification of any unit that had previously been in a Local Alarm condition. If a detector has entered a Local Alarm, when it exits that Local Alarm, the Alarm Memory latch is set. Initially the GLED can be used to visually identify any unit that had previously been in a Local Alarm condition. The GLED flashes three times spaced 1.3 seconds apart. This pattern will repeat every 43 seconds. The duration of the flash is 10 ms. In order to preserve battery power, this visual indication will stop after a period of 24 hours. The user will still be able to identify a unit with an active alarm memory by pressing the Push-to-Test button. When this button is active, the horn will chirp for 10 ms every 250 ms.

If the Alarm Memory condition is set, then any time the Push-to-Test button is pressed and released, the Alarm Memory latch is reset.

The initial 24 hour visual indication is not displayed if a low battery condition exists.

#### 3.8 End of Life Indicator

As an option, after every 14 days of continuous operation, the device will read a stored age count from the EEPROM and increment this count. After 10 years of powered operation, an audible warning will occur indicating that the unit should be replaced. This indicator will be similar to the chamber test failure warning in that the horn will pulse on three times for 10 ms separated by 330 ms every 43 seconds. This indicator will be separated from the low battery indicator by approximately 20 seconds.

#### 3.9 Photo Chamber Long Term Drift Adjustment

As an option, the design includes a Long Term Drift Adjustment for the photo chamber. If this option is selected, during calibration a normal no-smoke baseline integration measurement is made and stored in EEPROM. During normal operation, a new baseline is calculated by making 64 integration measurements over a period of 8 hours. These measurements are averaged and compared to the original baseline stored during calibration to calculate the long term drift. All four limits stored during calibration are adjusted by this drift factor. Drift sampling is suspended during Hush, Local Smoke and Remote Smoke conditions.

#### 4.0 USER PROGRAMMING MODES

#### TABLE 4-1: PARAMETRIC PROGRAMMING

Parametric Pr	ogramming	Ra	inge	Resol	ution	
IRED Period		100-	400 µs	100 µs		
IRED Current Sink		50-2	00 mA	50 r	nA	
Low Battery Detection	on Voltage	2.1 -	- 2.8V	100	mV	
Photo Detection Lim	its		Typical Maximun	n Input Current (nA)		
	-	100 µs	200 µs	300 µs	400 µs	
Normal/Hysteresis	GF = 1	58	29	19.4	14.5	
	GF = 2	29	14.5	9.6	7.2	
	GF = 3	14.5	7.2	4.8	3.6	
	GF = 4	7.2	3.6	2.4	1.8	
Hush	GF = 1	116	58	38.8 2		
	GF = 2	58	29	19.4	14.5	
	GF = 3	29	14.5	9.6	7.2	
	GF = 4	14.5	7.2	4.8	3.6	
Chamber Test	GF = 1	29	14.5	9.6	7.2	
	GF = 2	14.5	7.2	4.8	3.6	
	GF = 3	7.2	3.6	2.4	1.8	
	GF = 4	3.6	1.8	1.2	0.9	

**Note 1:** GF is the user selectable Photo Integration Gain Factor. Once selected, it applies to all modes of operation. For example, if GF = 1 and integration time is selected to be 100 μs, the ranges will be as follows: Normal/Hysteresis = 58 nA, Hush = 116 nA, Chamber Test = 29 nA.

2: Nominal measurement resolution in each case will be 1/31 of the maximum input range.

3: The same current resolution and ranges applies to the limits.

#### TABLE 4-2: FEATURES PROGRAMMING

Features	Options
Tone Select	Continuous or NFPA Tone
10 Year End-of-life Indicator	Enable/Disable
Photo Chamber Long Term Drift Adjustment	Enable/Disable
Low Battery Hush	Enable/Disable
Hush Options	Option 1: Hush mode is not cancelled for any reason. If the test button is pushed during Hush, the unit reverts to Normal Sensitivity to test the unit, but when it comes out of test, resumes in Hush where it left off.
	Option 2: The Hush mode is cancelled if the Reduced Sensitivity threshold is exceeded (high smoke level), and if an external (interconnect alarm) is signaled. If the test button is pushed during Hush, after the test is executed, the Hush mode is terminated.

#### 4.1 Calibration and Programming Procedures

Eleven separate programming and test modes are available for user customization. To enter these modes, after power-up, TEST2 must be driven to  $V_{DD}$  and held at that level. The TEST input is then clocked to step through the modes. FEED and IO are reconfigured to become test mode inputs, while RLED, GLED and HB become test mode outputs. The test mode functions for each pin are outlined in Table 4-3.

When TEST2 is held at  $V_{DD}$ , TEST becomes a tri-state input with nominal input levels at  $V_{SS}$ ,  $V_{DD}$  and  $V_{BST}$ . A TEST clock occurs whenever the TEST input switches from  $V_{SS}$  to  $V_{BST}$ . The TEST Data column represents the state of TEST when used as a data input, which would be either  $V_{SS}$  or  $V_{DD}$ . The TEST pin can therefore be used as both a clock, to change modes, and a data input, once a mode is set. Other pin functions are described in Section 4.2 "User Selections".

Mode	Description	TEST Clock	TEST Data	TEST2	FEED	ю	RLED	GLED	НВ
	V <sub>IH</sub>	V <sub>BST</sub>	V <sub>DD</sub>	V <sub>DD</sub>	V <sub>BST</sub>	V <sub>DD</sub>	—	—	—
	V <sub>IL</sub>	$V_{SS}$	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>SS</sub>		_	—
Т0	Photo Gain Factor (2 bits)	0	ProgData	V <sub>DD</sub>	ProgCLK	ProgEn 14 bits	RLED	GLED	HB
	Integ Time (2 bits)	0	ProgData	V <sub>DD</sub>	ProgCLK	ProgEn 14 bits	RLED	GLED	HB
	IRED Current (2 bits)	0	ProgData	V <sub>DD</sub>	ProgCLK	ProgEn 14 bits	RLED	GLED	HB
	Low Battery Trip (3 bits)	0	ProgData	V <sub>DD</sub>	ProgCLK	ProgEn 14 bits	RLED	GLED	HB
	LTD Enable (1 bit)	0	ProgData	V <sub>DD</sub>	ProgCLK	ProgEn 14 bits	RLED	GLED	HB
	Hush Option (1 bit)	0	ProgData	V <sub>DD</sub>	ProgCLK	ProgEn 14 bits	RLED	GLED	HB
	LB Hush Enable (1 bit)	0	ProgData	V <sub>DD</sub>	ProgCLK	ProgEn 14 bits	RLED	GLED	HB
	EOL Enable (1 bit)	0	ProgData	V <sub>DD</sub>	ProgCLK	ProgEn 14 bits	RLED	GLED	HB
	Tone Select (1 bit)	0	ProgData	V <sub>DD</sub>	ProgCLK	ProgEn 14 bits	RLED	GLED	HB
T1	Norm Lim Set (5 bits) <sup>(</sup> 4 <sup>)</sup>	1	not used	V <sub>DD</sub>	CalCLK	LatchLim <sup>(</sup> 3)	Gamp	IntegOut	SmkComp <sup>(1)</sup>
T2	Hyst Lim Set (5 bits) <sup>(</sup> 4 <sup>)</sup>	2	not used	V <sub>DD</sub>	CalCLK	LatchLim <sup>(</sup> 3)	Gamp	IntegOut	SmkComp <sup>(1)</sup>
Т3	Hush Lim Set (5 bits) <sup>(</sup> 4 <sup>)</sup>	3	not used	V <sub>DD</sub>	CalCLK	LatchLim <sup>(</sup> 3)	Gamp	IntegOut	SmkComp <sup>(1)</sup>
T4	Ch Test Lim Set (5 bits) <sup>(</sup> 4 <sup>)</sup>	4	not used	V <sub>DD</sub>	CalCLK	LatchLim <sup>(</sup> 3)	Gamp	IntegOut	SmkComp <sup>(1)</sup>
T5	LTD Baseline (5 bits)	5	not used	V <sub>DD</sub>	MeasEn	ProgEn 25 bits	Gamp	IntegOut	SmkComp <sup>(1)</sup>
T6	Serial Read/Write	6	ProgData	V <sub>DD</sub>	ProgCLK	ProgEn	RLED	GLED	Serial Out
Τ7	Norm Lim Check	7	not used	V <sub>DD</sub>	MeasEn	not used	Gamp	IntegOut	SCMP <sup>(</sup> 2)
T8	Hyst Lim Check	8	not used	V <sub>DD</sub>	MeasEn	not used	Gamp	IntegOut	SCMP <sup>(</sup> 2 <sup>)</sup>
Т9	Hush Lim Check	9	not used	V <sub>DD</sub>	MeasEn	not used	Gamp	IntegOut	SCMP <sup>(</sup> 2)
T10	Ch Test Lim Check	10	not used	V <sub>DD</sub>	MeasEn	not used	Gamp	IntegOut	SCMP <sup>(</sup> 2 <sup>)</sup>
T11	Horn Test	11	not used	V <sub>DD</sub>	FEED	HornEn	RLED	GLED	HB

**Note 1:** SmkComp (HB) – digital comparator output (high if Gamp < IntegOut; low if Gamp > IntegOut)

2: SCMP (HB) – digital output representing comparison of measurement value and associated limit. Signal is valid only after MeasEn has been asserted and measurement has been made. (SCMP high if measured value > limit; low if measured value < limit).

**3:** LatchLim (IO) – digital input used to latch present state of limits (Gamp level) for later storage. T1-T4 limits are latched, but not stored until ProgEn is asserted in T5 mode.

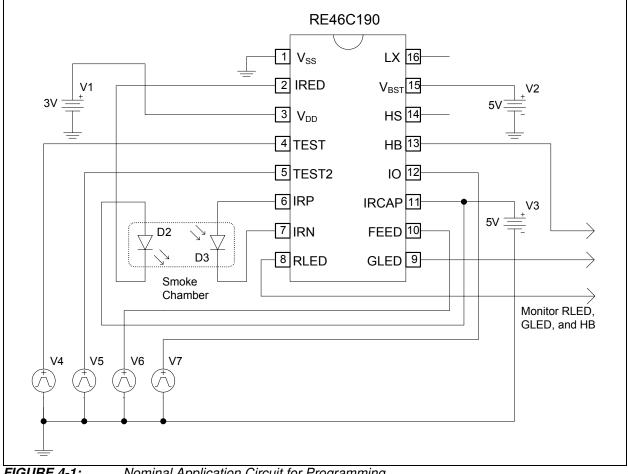
4: Operating the circuit in this manner with nearly continuous IRED current for an extended period of time may result in undesired or excessive heating of the part. The duration of this step should be minimized.

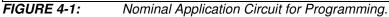
#### 4.2 **User Selections**

Prior to smoke calibration, the user must program the functional options and parametric selections. This requires that 14 bits, representing selected values, be clocked in serially using TEST as a data input and FEED as a clock input, and then be stored in the internal EEPROM.

The detailed steps are as follows:

1. Power up with bias conditions as shown in Figure 4-1. At power-up TEST = TEST2 = FEED =  $IO = V_{SS}$ .





## RE46C190

- 2. Drive TEST2 input from  $V_{SS}$  to  $V_{DD}$  and hold at  $V_{DD}$  through Step 5 below.
- 3. Using TEST as data and FEED as clock, shift in values as selected from Register 4-1.

Note: For test mode T0 only 14 bits (bits 25-38) will be loaded. For test mode T6 all 39 bits (bits 0-38), will be loaded.

#### REGISTER 4-1: CONFIGURATION AND CALIBRATION SETTINGS REGISTER

	W-x	W-x	W-x	W-x	W-x	W-x	W-x			
	TS	EOL	LBH	HUSH	LTD	LB0	LB1			
	bit 38						bit 32			
W-x	W-x	W-x	W-x	W-x	W-x	W-x	W-x			
LB2	IRC1	IRC0	IT1	IT0	PAGF1	PAGF0	NL4			
bit 31		iiteo	111	110	TAGET	TAGEU	bit 2			
							Sit 2			
W-x	W-x	W-x	W-x	W-x	W-x	W-x	W-x			
NL3	NL2	NL1	NL0	HYL4	HYL3	HYL2	HYL1			
bit 23							bit 10			
W-x	W-x	W-x	W-x	W-x	W-x	W-x	W-x			
HYLO	HUL4	HUL3	HUL2	HUL1	HULO	CTL4	CTL3			
bit 15		11020			11020	0121	bit			
W-x	W-x	W-x	W-x	W-x	W-x	W-x	W-x			
CTL2	CTL1	CTL0	LTD4	LTD3	LTD2	LTD1	LTD0			
bit 7							bit			
Legend:										
R = Readab	le bit	W = Writable	bit	U = Unimplei	mented bit, rea	d as '0'				
-n = Value at POR		'1' = Bit is set		'0' = Bit is cleared		x = Bit is unknown				
bit 38	TS: Tone Select bit									
		<ul><li>1 = Temporal Horn Pattern</li><li>0 = Continuous Horn Pattern</li></ul>								
bit 37										
51	1 = Enable	EOL: End of Life Enable bit								
	0 = Disable									
bit 36	LBH: Low Battery Hush Enable bit									
	1 = Enable									
	0 = Disable									
bit 35	<ul> <li>HUSH: Hush Option bit</li> <li>1 = Cancelled for high smoke level, interconnect alarm, or second push of TEST button</li> </ul>									
	(as described above)									
	0 = Never Cancel									
bit 34	LTD: Long Term Drift Enable bit									
	1 = Enable									
	0 = Disable	0 = Disable								

REGISTER 4	l-1:	CONFIGURATION AND CALIBRATION SETTINGS REGISTER (CONTINUED)
bit 33-31	000 001 010 011 100 101 110	0:2>: Low Battery Trip Point bits = 2.1V = 2.5V = 2.3V = 2.3V = 2.7V = 2.2V = 2.6V = 2.4V = 2.4V
bit 30-29		<1:0>: IRED Current bits
	01 = 10 =	50 mA 100 mA 150 mA 200 mA
bit 28-27		:0>: Integration Time bits
	01 = 10 =	400 μs 300 μs 200 μs 100 μs
bit 26-25		F<1:0>: Photo Amplifier Gain Factor bits
	00 = 01 = 10 = 11 =	23
bit 24-20		4:0>: Normal Limits bits (Section 3.2)
	000	00 = 0 01 = 1
	•	
	•	
		10 = 30 11 = 31
bit 19-15		<4:0>: Hysteresis Limits bits (Section 3.2)
		00 = 0 01 = 1
	•	
	•	
		10 = 30 11 = 31
bit 14-10	<b>HUL</b>	<4:0>: Hush Limits bits (Section 3.6) 00 = 0 01 = 1
	•	-
	•	
	•	10 <b>= 30</b>
		11 = 31

#### REGISTER 4-1: CONFIGURATION AND CALIBRATION SETTINGS REGISTER (CONTINUED)

The minimum pulse width for FEED is 10  $\mu$ s, while the minimum pulse width for TEST is 100  $\mu$ s. For example, for the following options, the sequence would be:

 data 0
 0
 1
 1
 0
 0
 1
 0
 0
 0
 1
 1
 0
 0
 0
 1
 1
 0
 0
 1
 1
 0
 0
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 1
 1</t

 After shifting in data, pull IO input to V<sub>DD</sub>, then V<sub>SS</sub> (minimum pulse width of 10 ms) to store shift register contents into the memory.

5. If any changes are required, power down the part and return to Step 1. All bit values must be reentered.

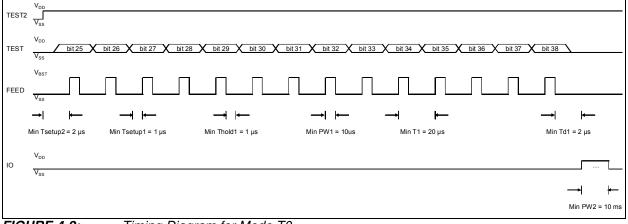


FIGURE 4-2:

Timing Diagram for Mode T0.

As an alternative to Figure 4-1, Figure 4-3 can be used to program while in the application circuit. Note that in addition to the five programming supplies, connections to  $V_{SS}$  are needed at TP1 and TP2.

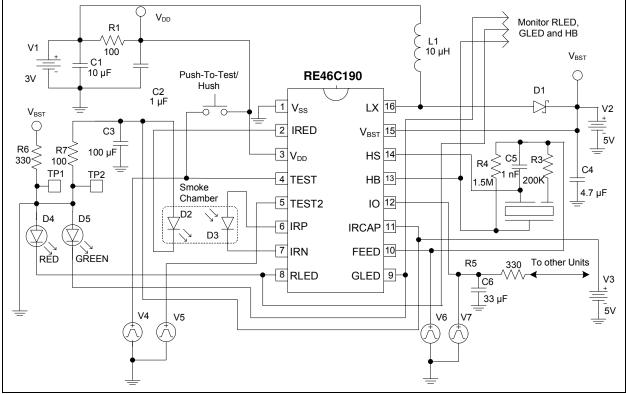


FIGURE 4-3: Circuit for Programming in the Typical Application.

#### 4.3 Smoke Calibration

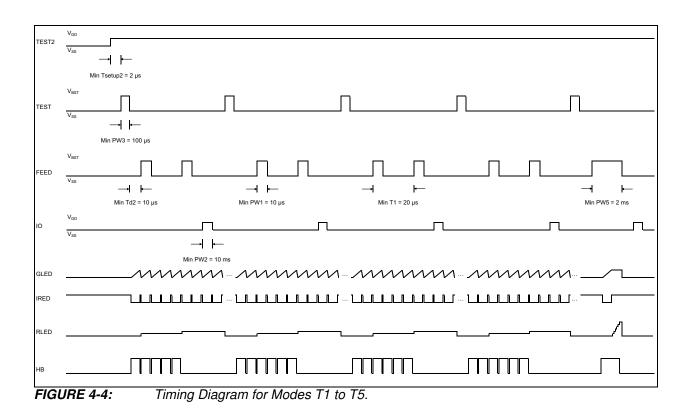
A separate calibration mode is entered for each measurement mode (Normal, Hysteresis, Hush and Chamber Test) so that independent limits can be set for each. In all calibration modes, the integrator output can be accessed at the GLED output.

The Gamp output voltage, which represents the smoke detection level, can be accessed at the RLED output. The SmkComp output voltage is the result of the comparison of Gamp with the integrator output, and can be accessed at HB. The FEED input can be clocked to step up the smoke detection level at RLED. Once the desired smoke threshold is reached, the TEST input is pulsed low to high to store the result.

The procedure is described in the following steps:

- 1. Power up with the bias conditions shown in Figure 4-1.
- Drive TEST2 input from V<sub>SS</sub> to V<sub>DD</sub> to enter the Programming mode. TEST2 should remain at V<sub>DD</sub> through Step 8 described below.
- 3. Apply a clock pulse to the TEST input to enter in T1 mode. This initiates the calibration mode for Normal Limits setting. The Integrator output saw tooth should appear at GLED and the smoke detection level at RLED. Clock FEED to increase the smoke detection level as needed. Once the desired smoke threshold is reached, the IO input is pulsed low to high to enter the result. See typical waveforms in Figure 4-4. Operating the circuit in this manner, with nearly continuous IRED current for an extended period of time, may result in undesired or excessive heating of the part. The duration of this step should be minimized.
- 4. Apply a second clock pulse to the TEST input to enter in T2 mode. This initiates the calibration mode for Hysteresis Limits. Clock FEED as in Step 3 and apply pulse to IO, once desired level is reached.Operating the circuit in this manner, with nearly continuous IRED current for an extended period of time, may result in undesired or excessive heating of the part. The duration of this step should be minimized.

- 5. Apply a clock pulse to the TEST input again to enter in T3 mode and initiate calibration for Hush Limits. Clock FEED as in the steps above and apply a pulse to IO, once the desired level is reached. Operating the circuit in this manner, with nearly continuous IRED current for an extended period of time, may result in undesired or excessive heating of the part. The duration of this step should be minimized.
- 6. Apply a clock pulse to the TEST input a fourth time to enter in T4 mode, and initiate the calibration for Chamber Test Limits. Clock FEED and apply pulse to IO, once desired level is reached. Operating the circuit in this manner, with nearly continuous IRED current for an extended period of time, may result in undesired or excessive heating of the part. The duration of this step should be minimized.
- 7. If the Long Term Drift Adjustment is enabled, after all limits have been set, the long term drift (LTD) baseline measurement must be made. To do this, a measurement must be made under no-smoke conditions. To enable the baseline measurement, pull TEST from  $V_{SS}$  to  $V_{BST}$  again and return to  $V_{SS}$ . Once the chamber is clear, pulse FEED low to high to make the baseline measurement.
- 8. After limits have been set and baseline LTD measurement has been made, pulse IO to store all results in memory. Before this step, no limits are stored in memory.



#### 4.4 Serial Read/Write

As an alternative to the steps in **Section 4.3 "Smoke Calibration**", if the system has been well characterized, the limits and baseline can be entered directly from a serial read/write calibration mode.

To enter this mode, follow these steps:

- 1. Set up the application as shown in Figure 4-1.
- 2. Drive TEST2 input from  $V_{SS}$  to  $V_{DD}$  to enter in Programming mode. TEST2 should remain at  $V_{DD}$  until all data has been entered.
- Clock the TEST input to mode T6 (High = V<sub>BST</sub>, Low = V<sub>SS</sub>, 6 clocks). This enables the serial read/write mode.
- 4. TEST now acts as a data input (High =  $V_{DD}$ , Low =  $V_{SS}$ ). FEED acts as the clock input (High =  $V_{BST}$ , Low =  $V_{SS}$ ). Clock in the limits, LTD baseline, functional and parametric options. The data sequence should be as follows:
- 5 bit LTD sample (LSB first)
- 5 bit Chamber Test Limits (LSB first)
- 5 bit Hush Limits (LSB first)
- 5 bit Hysteresis Limits (LSB first),

5 bit Normal Limits (LSB first)

Then, the data sequence follows the pattern described in Register 4-1:

- 2 bit Photo Amp Gain Factor
- 2 bit Integration Time
- 2 bit IRED current
- 3 bit Low Battery Trip Point
- 1 bit Long Term Drift Enable
- 1 bit Hush Option
- 1 bit Low Battery Hush Enable
- 1 bit EOL enable
- 1 bit Tone Select

A serial data output is available at HB.

5. After all 39 bits have been entered, pulse IO to store into the EEPROM memory.

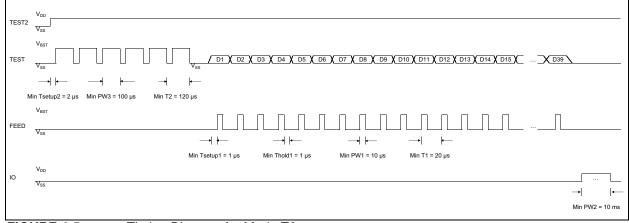


FIGURE 4-5:

Timing Diagram for Mode T6.

#### 4.5 Limits Verification

After all limits and LTD baseline have been entered and stored into the memory, additional test modes are available to verify if the limits are functioning as expected. Table 4-4 describes several verification tests.

#### TABLE 4-4:LIMITS VERIFICATION DESCRIPTION

Limit	Test Description
Normal Limits	Clock TEST to Mode T7 (7 clocks). With appropriate smoke level in chamber, pull FEED to $V_{DD}$ and hold for at least 1 ms. The HB output will indicate the detection status (High = smoke detected).
Hysteresis Limits	Clock TEST to Mode T8 (8 clocks). Pulse FEED and monitor HB as in Normal Limits case.
Hush Limits	Clock TEST to Mode T9 (9 clocks). Pulse FEED and monitor HB.
Chamber Test Limits	Clock TEST to Mode T10 (10 clocks). Pulse FEED and monitor HB.

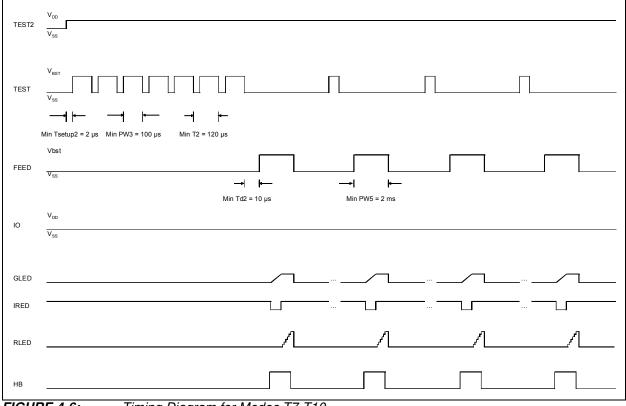


FIGURE 4-6: Timing Diagram for Modes T7-T10.